



# SOT873-1

DFN3333-8: plastic thermal enhanced very thin small outline package; no leads; 8 terminals

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DFN3333-8
<b>Package type industry code</b>	DFN3333-8
<b>Package style descriptive code</b>	HVSON (thermal enhanced very thin small outline; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	19-4-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.2	-	3.3	3.4	mm
E	package width	3.2	-	3.3	3.4	mm
A	seated height	[tbd]	-	[tbd]	1	mm
e	nominal pitch	-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	8	-	

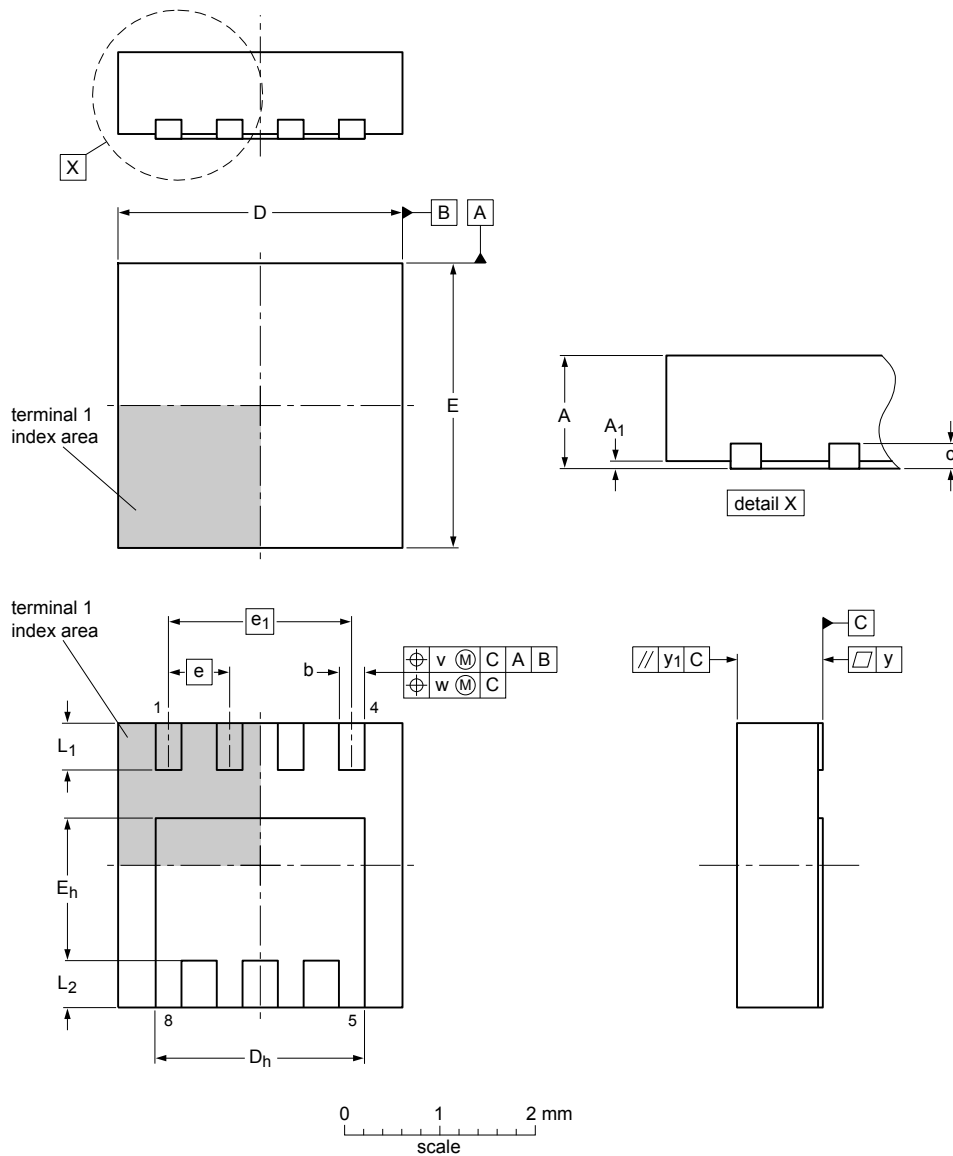


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## 2. Package outline

DFN3333-8: plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 3.3 x 3.3 x 1.0 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>max.</sub>	A <sub>1</sub>	b	c	D	D <sub>h</sub>	E	E <sub>h</sub>	e	e <sub>1</sub>	L <sub>1</sub>	L <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	1	0.05 0.00	0.45 0.25	0.2	3.4 3.2	2.4 2.2	3.4 3.2	1.80 1.58	0.65	1.95	0.55 0.45	0.52 0.35	0.1	0.05	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT873-1	---	---	---			10-04-19 11-12-01

Fig. 1. Package outline DFN3333-8 (SOT873-1)

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### 3. Soldering

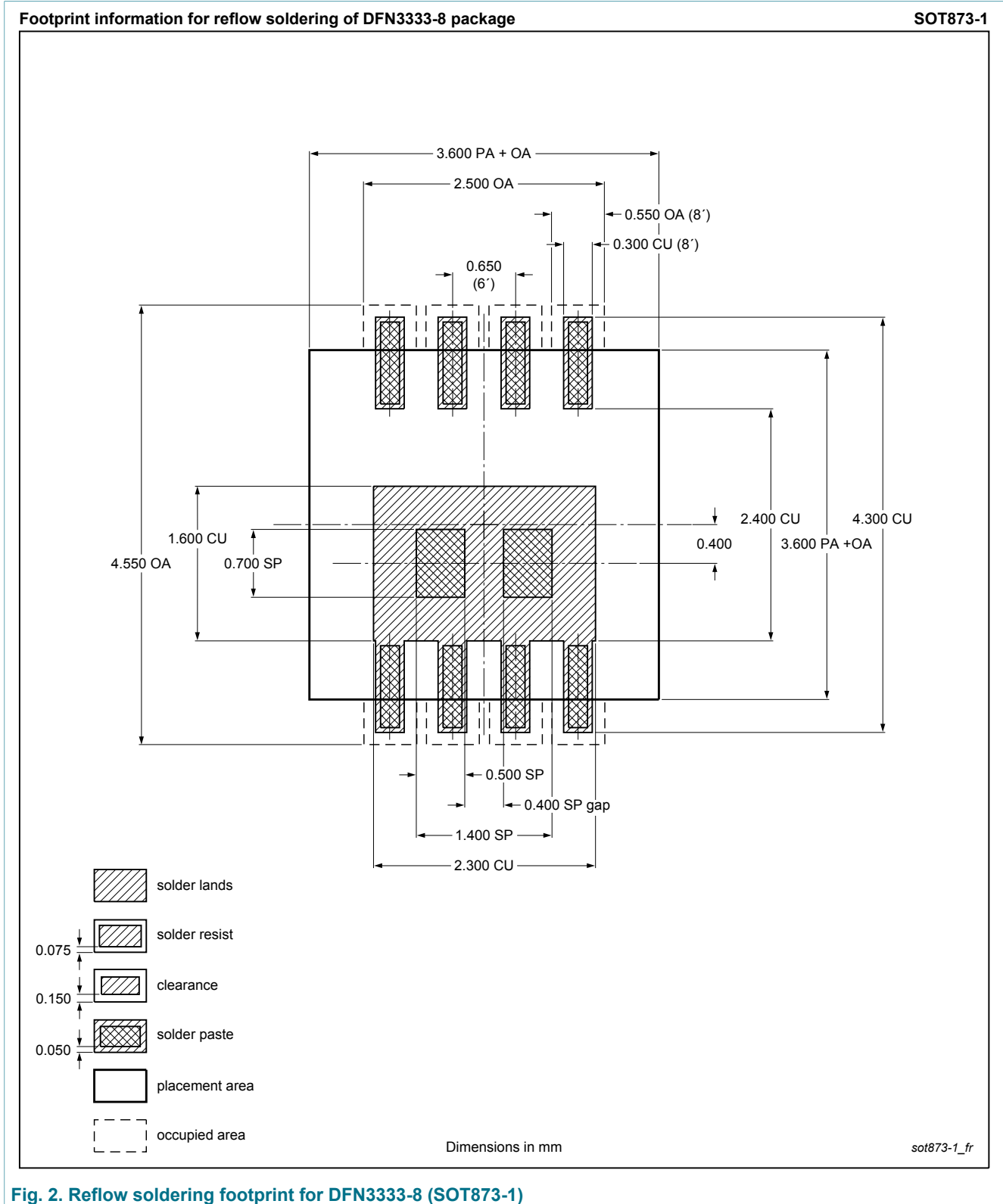


Fig. 2. Reflow soldering footprint for DFN3333-8 (SOT873-1)

## 4. Legal information

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